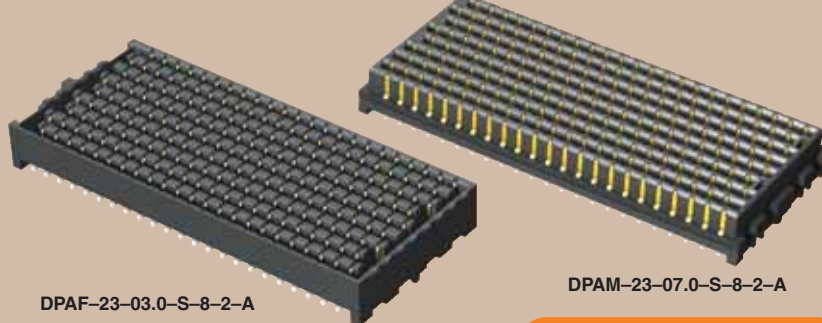


(2,16 mm) .085"



DPAM-23-03.0-S-8-2-A

DPAM-23-07.0-S-8-2-A

DPAM, DPAF SERIES

HIGH DENSITY DIFFERENTIAL PAIR ARRAY

DPAM Mates with:
DPAF

DPAF Mates with:
DPAM

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAM or www.samtec.com?DPAF

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Plating:

Au over 50µ" (1,27 µm) Ni

Current Rating (2x3):

2.9 A per pin

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10.4mΩ

Working Voltage:

300 VAC

Mated Cycles: 100 Cycles

RoHS Compliant: Yes

Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Protocols Supported

Fibre Channel

Rapid I/O

PCI Express®

SATA

InfiniBand™

XAUI

MGT (Rocket I/O)

Download app notes at:

www.samtec.com/appnote

Contact SIG @ samtec.com

for questions on protocols

ALSO AVAILABLE
(MOQ Required)

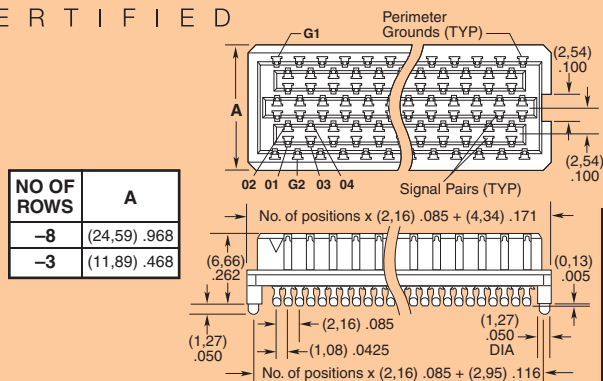
- Tin-Lead Solder Charge
- Other platings
- Contact Samtec.

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

DPAM	PAIRS PER ROW	07.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-04, -06 -08, -15, -23		-S =30µ" (0,76 µm) Gold on contact area, Tin on solder tail	-8 =Eight Pair Rows -3 =Three Pair Rows	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3% Ag/.5% Cu Solder Crimp		-K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel -GP =Guide Post (-23 only)

Final Inch
CERTIFIED



NO OF ROWS	A
-8	(24,59) .968
-3	(11,89) .468

DPAM/DPAF 10 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	7 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB. Complete test data available at www.samtec.com?DPAM, www.samtec.com?DPAF or contact sig@samtec.com

DPAF	PAIRS PER ROW	03.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-04, -06, -08, -15, -23		-S =30µ" (0,76 µm) Gold on contact area, Tin on solder tail	-8 =Eight Pair Rows -3 =Three Pair Rows	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp		-K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel

NO OF ROWS	A
-8	(23,32) .918
-3	(10,62) .418

SIZE	USABLE PAIRS PER ARRAY*
-04 x -3	6 Pairs
-06 x -3	12 Pairs
-04 x -8	16 Pairs
-06 x -8	32 Pairs
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs

*Assumes first and last pair in each row are grounded

DPAM LEAD STYLE	DPAF MATED HEIGHT*
-07.0	10 mm

*Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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SAMTEC USA • Tel: +1-800-SAMTEC-9 or +1-812-944-6733 SAMTEC NORTHERN CALIFORNIA • Tel: +1-408-395-5900 SAMTEC SOUTHERN CALIFORNIA • Tel: +1-800-726-8329
 SAMTEC SOUTH AMERICA • Tel: +55 31 3786 3227 SAMTEC UNITED KINGDOM • Tel: +44 01236 739292 SAMTEC GERMANY • Tel: +49 (0) 89 / 89460-0
 SAMTEC FRANCE • Tel: +33 1 60 95 06 60 SAMTEC ITALY • Tel: +39 039 6890337 SAMTEC NORDIC/BALTIC • Tel: +46 8 4477280 SAMTEC BENELUX • Tel: +44 01236 739292
 SAMTEC ISRAEL • Tel: +972 3 7526600 SAMTEC INDIA • Tel: +91 80 3272 1612 SAMTEC ANZ • Tel: +613 9580 0683 SAMTEC SINGAPORE • Tel: +65 6745 5955 SAMTEC JAPAN • Tel: +81 45 475 1385
 SAMTEC SHANGHAI • Tel: +86 21 6083 3766 SAMTEC SHENZHEN • Tel: +86 755 83776780 SAMTEC TAIWAN • Tel: +886 2 2735 6109 SAMTEC HONG KONG • Tel: +852 26904658 SAMTEC KOREA • Tel: +82 31 717 5685